

ABSTRACTA MICRO-CHIP FUSE AND METHOD OF
MANUFACTURING THE SAME

A micro-chip fuse and a method of manufacturing the same is disclosed which includes a fusible element made of a metallic film that is formed by a deposition process. Through-bores (20) are provided through a first substrate (2) and filled with a photosensitive resist (1) to make smooth the surface of the first substrate. After curing the resist, metal is deposited on the surface of the first substrate to form a metallic film (5). A photosensitive resist (21) is applied to the metallic film (5) and a photomask (6) is placed on the resist (21) to effect an exposure and a development. The metallic film is etched and the resists are removed to form the fusible elements (7) made of the metallic film extending over the through-bores. A second substrate (8) is placed under the first substrate (2), and a third substrate (10) including recesses (30) for covering the through-bores (20) is placed on the first substrate (2) to laminate them. Electrodes (13) are provided on the ends of the substrates. The laminated substrates are divided into individual micro-chip fuses (14).

To be accompanied when published by Figure 1A of the accompanying drawings.

